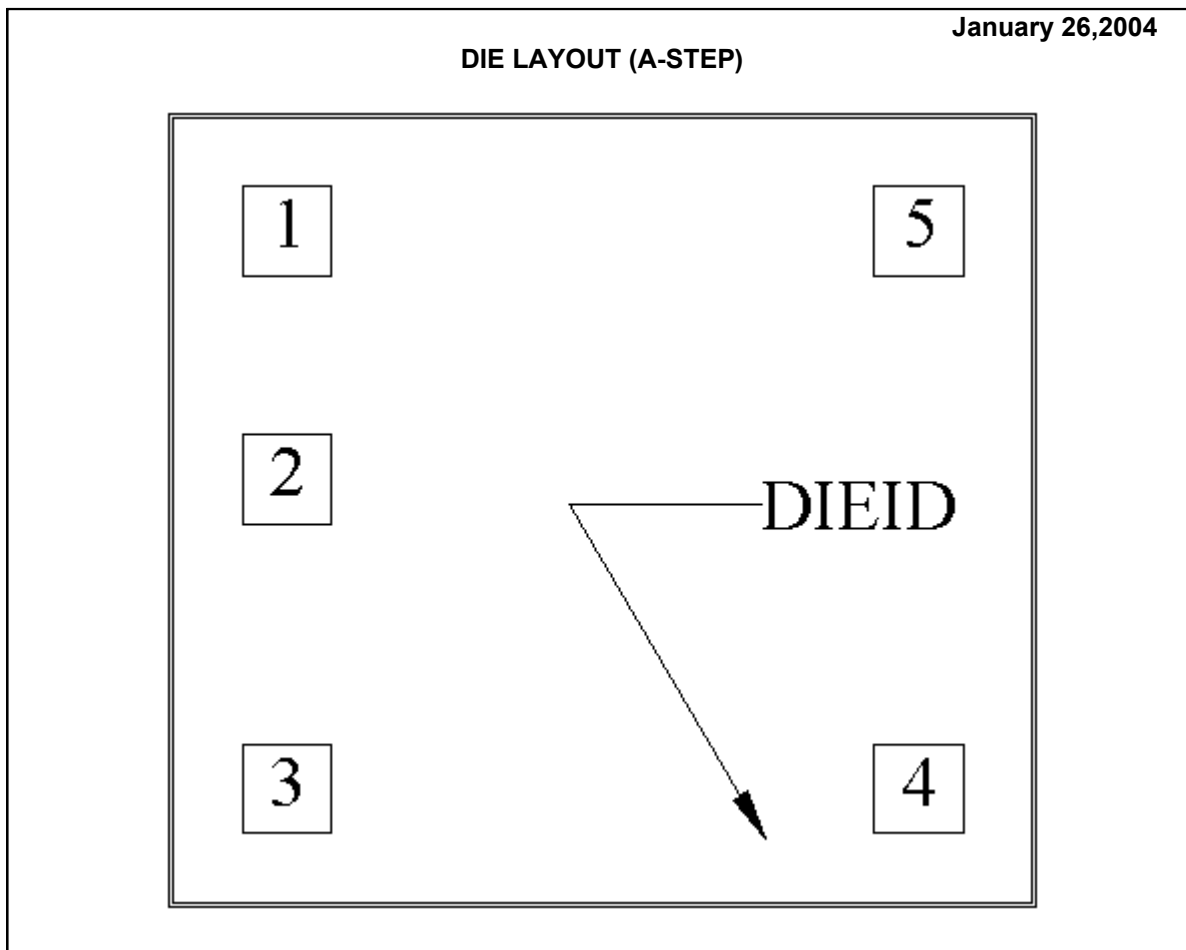


LMH6624 MDC MWC
ULTRA LOW NOISE WIDEBAND OPERATIONAL AMPLIFIER



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LMH6624A	Bond Pad Opening Size (min)	90µm x 90µm
Die Step	A	Bond Pad Metalization	0.5% COPPER_BAL. ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	876µm x 800µm 34.5mils x 31.5mils	Back Side Connection	V-
Thickness	254µm Nominal		
Min Pitch	250µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	XY COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
OUTPUT	1	-319	282	90	x	90
V -	2	-319	31	90	x	90
V+	3	-319	-282	90	x	90
INPUT -	4	319	-282	90	x	90
INPUT +	5	319	282	90	x	90

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IN U.S.A.

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Fax: 1 207 541 6140

IN EUROPE

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Fax: 49 (0) 8141 351470

IN ASIA PACIFIC

Tel: (852) 27371701

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